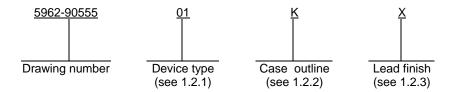
							R	EVISI	ONS										
LTR				DI	ESCR	IPTIO	N					DA	TE (YF	R-MO-	·DA)		APPF	ROVE)
А		te drawing to current requirements. Editorial changes ghout gap					02-02-21			Ray	mond	Monni	n						
В	Add QP Se	emicon rougho	ductor	as an	appro	oved s	ource	of sup	pply an	d edite	orial		06-0	6-22		Ray	mond	Monni	n
REV SHEET	AL FIRST PA	AGE OF	THIS	S DRA	WING	HAS	BEEN	REPL	ACEC)									
REV SHEET REV	AL FIRST PA	AGE OF	F THIS	S DRA	WING	HAS	BEEN	REPL	ACED)									
REV SHEET REV SHEET		AGE OF			WING														
REV SHEET REV SHEET REV STATUS	S	AGE OF	REV	,	WING	В	В	В	В	В	В	В	В	В	В	В	В	В	
REV SHEET REV SHEET REV STATUS OF SHEETS	S	AGE OF		,	WING						B 6	B 7	B 8	B 9	B 10	B 11	B 12	B 13	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	S	AGE OF	REV SHE	, EET PARE	D BY Rajes	В	B 2	В	В	B 5	6 EFEN	7 SE SI	8 UPPL	9 Y CE	10	11	12 _UMB	13	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	S		REV SHE	, , , , , , , , , , , , , , , , , , ,	D BY Rajes	B 1	B 2	В	В	B 5	6 EFEN	7 SE SI	8 UPPLIBUS,	9 Y CE	10	11 R COL 218-3	12 _UMB	13	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STAN MICRO DRA THIS DE AVA FOR US DEPAR	NDARD OCIRCUIT AWING RAWING IS AILABLE SE BY ALL RTMENTS NCIES OF TH	·	REV SHE PREI	CKED Ken	D BY Rajes BY neth S	B 1 sh Pith	B 2 nadia	B 3	B 4	B 5 DECROCE TIME	EFEN CC CIRCU	7 SE SI DLUM http JIT, N	BUS, S://ww	9 Y CE, OHIO	NTER D 432 cc.dl	11 R COL 218-3 a.mil	12 -UMB 990	13 US	JS
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STAN MICRO DRA THIS DE AVA FOR US DEPAR AND AGEN DEPARTMEN	NDARD OCIRCUIT AWING RAWING IS AILABLE SE BY ALL RTMENTS NCIES OF TH	·	REV SHE PREI	CKED Ken PROVE Mich	D BY Rajes BY neth S	B 1 Sh Pith Frye ROVAI 92-08	B 2 nadia	B 3	B 4	B 5 DE CROCE E TIM DGRA NOLI	EFEN CO CIRCI ME PI AMM ITHIC	SE SI DLUM http JIT, N ROGI ABLE	BUS, OE//WW	9 Y CE, OHIO	NTER O 432 CC.dl	11 R COL 218-3 a.mil ITAL SYN CE,	12 -UMB 990 , CMC	13 S US	

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
 - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function	<u>t_{PD}</u>
01	C20RA10	Asynchronous PLD	35 ns
02	C20RA10	Asynchronous PLD	25 ns
03	C20RA10	Asynchronous PLD	20 ns

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
K	GDFP2-F24 or CDFP3-F24	24	Flat pack
L	GDIP3-T24 or CDIP4-T24	24	Dual-in-line
3, X	CQCC1-N28	28	Square leadless chip carrier

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings. 1/

Supply voltage to ground potential	
DC voltage applied to outputs in high Z state	
DC input voltage	
Maximum power dissipation (P _D) <u>2</u> /	
Lead temperature (soldering, 10 seconds)	
Thermal resistance, junction-to-case (θ_{JC}):	See MIL-STD-1835
Junction temperature (T _J)	+175°C
Storage temperature range	-65°C to +150°C
Temperature under bias	-55°C to +125°C
Output current into outputs (low)	-16 mA

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 2

^{1/} Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

^{2/} Must withstand the added P_D due to short circuit test; e.g., I_{OS}.

1.4 Recommended operating conditions.

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at http://assist.daps.dla.mil/quicksearch/ or http:

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 3

- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
 - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
 - 3.2.3 Truth table. The truth table shall be as specified on figure 2.
- 3.2.3.1 <u>Unprogrammed devices</u>. The truth table for unprogrammed devices for contracts involving no altered item drawing shall be as specified on figure 2. When required in groups A, B, C, or D (see 4.3), the devices shall be programmed by the manufacturer prior to test. A minimum of 50 percent of the total number of cells shall be programmed or at least 25 percent of the total number of cells to any altered item drawing.
- 3.2.3.2 <u>Programmed devices</u>. The truth table for programmed devices shall be as specified by an attached altered item drawing.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark.</u> A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
 - 3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Processing options</u>. Since the device is capable of being programmed by either the manufacturer or the user to result in a wide variety of configurations; two processing options are provided for selection in the contract, using an altered item drawing.
- 3.10.1 <u>Unprogrammed device delivered to the user</u>. All testing shall be verified through group A testing as defined in 3.2.3.1 and table II. It is recommended that users perform subgroups 7 and 9 after programming to verify the specific program configuration.
- 3.10.2 <u>Manufacturer-programmed device delivered to the user</u>. All testing requirements and quality assurance provisions herein, including the requirements of the altered item drawing, shall be satisfied by the manufacturer prior to delivery.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 4

TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol	Conditions $ -55^{\circ}C \leq T_{C} \leq +125^{\circ}C $ $ 4.5 \text{ V} \leq V_{CC} \leq 5.5 \text{ V} $	Group A subgroups	Device type	Li	mits	Unit
		unless otherwise specified			Min	Max	
Output high voltage	V _{OH}	$V_{CC} = 4.5 \text{ V}, I_{OH} = -2.0 \text{ mA},$ $V_{IN} = V_{IH}, V_{IL}$	1, 2, 3	All	2.4		V
Output low voltage	V _{OL}	$V_{CC} = 4.5 \text{ V}, I_{OL} = 8.0 \text{ mA},$ $V_{IN} = V_{IH}, V_{IL}$	1, 2, 3	All		0.5	V
Input high voltage 1/	V _{IH}		1, 2, 3	All	2.0		V
Input low voltage 1/	V _{IL}		1, 2, 3	All		0.8	V
Input leakage current	I _{IX}	V _{IN} = 5.5 V to GND	1, 2, 3	All	-10	10	μΑ
Output leakage current	I _{OZ}	$V_{CC} = 5.5 \text{ V},$ $V_{OUT} = 5.5 \text{ V} \text{ and GND}$	1, 2, 3	All	-40	40	μΑ
Output short circuit current 2/3/	I _{os}	$V_{CC} = 5.5 \text{ V},$ $V_{OUT} = 0.5 \text{ V}$	1, 2, 3	All	-30	-90	mA
Standby power supply current	I _{CC1}	$V_{CC} = 5.5 \text{ V}, I_{OUT} = 0 \text{ mA},$ $V_{IN} = \text{GND}$	1, 2, 3	All		80	mA
Power supply current at frequency 3/	I _{CC2}	$V_{CC} = 5.5 \text{ V}, I_{OUT} = 0 \text{ mA},$ $V_{IN} = 0 \text{ to } 3 \text{ V}, f = f_{MAX}$	1, 2, 3	All		85	mA
Input capacitance 3/	C _{IN}	$V_{CC} = 5.0 \text{ V}$ $T_A = +25^{\circ}\text{C}, f = 1 \text{ MHz}$	4	All		10	pF
Output capacitance 3/	C _{OUT}	(see 4.3.1c)	4	All		10	pF
Functional tests		see 4.3.1d	7, 8A, 8B	All	L	Н	V
Input or feedback to	t _{PD}		9, 10, 11	01		35	ns
nonregistered output <u>4</u> /				02		25	
<u>-</u>				03		20	
Input to output enable	t _{EA}		9, 10, 11	01		35	ns
<u>5</u> /				02		30	
				03		20	

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 5

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol	Conditions $ -55^{\circ}C \leq T_{C} \leq +125^{\circ}C \\ 4.5 \text{ V} \leq V_{CC} \leq 5.5 \text{ V} $	Group A subgroups	Device type	Lir	mits	Unit
		unless otherwise specified			Min	Max	
Input to output disable	t _{ER}		9, 10, 11	01		35	ns
<u>3</u> / <u>5</u> /				02		30	
				03		20	
OE to output enable	t_{PZX}		9, 10, 11	01		25	ns
<u>5</u> /				02		20	
				03		15	
OE to output disable	t _{PXZ}		9, 10, 11	01		25	ns
<u>3</u> / <u>5</u> /				02		20	
				03		15	
Clock to output 4/	t _{CO}		9, 10, 11	01		35	ns
				02		25	
				03		20	
Input or feedback	t _{SU}		9, 10, 11	01	20		ns
setup time 4/				02	15		
				03	10		
Hold time 4/	t _H		9, 10, 11	01, 02	5		ns
				03	3		
Clock period	t _P		9, 10, 11	01	55		ns
$(t_{SU} + t_{CO}) \frac{4}{}$				02	40		
				03	30		
Clock width high 4/	t_{WH}		9, 10, 11	01	25		ns
				02	18		
				03	12		
Clock width low 4/	t_{WL}		9, 10, 11	01	25		ns
				02	18		
				03	12		

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 6

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol		Group A subgroups	Device type	Liı	mits	Unit
		unless otherwise specified			Min	Max	
Maximum frequency	f _{MAX}		9, 10, 11	01	18.1		MHz
(1/(t _P)) <u>3</u> / <u>4</u> /				02	25.0		
				03	33.3		
Input to asynchronous	t _S		9, 10, 11	01		40	ns
set of registered				02		25	
output <u>4</u> /				03		20	
Input to asynchronous	t_R		9, 10, 11	01		40	ns
reset of registered				02		25	
output <u>4</u> /				03		20	
Asynchronous set/reset	t _{AR}		9, 10, 11	01	20		ns
recovery time 4/				02	15		
				03	12		
Preload pulse width 4/	t _{WP}		9, 10, 11	All	15		ns
Preload setup time 3/ 4/	t _{SUP}		9, 10, 11	All	15		ns
Preload hold time 3/ 4/	t _{HP}		9, 10, 11	All	15		ns

- 1/ These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- For test purposes, not more than one output at a time should be shorted. Short circuit test duration should not exceed 1 second. V_{OUT} = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 3/ Tested initially and after any design or process changes that affect that parameter, and therefore shall be guaranteed to the limits specified in table I.
- 4/ AC tests are performed with input rise and fall times of 5 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V, and the output load on figure 3, circuit A. See figure 4 for waveforms.
- 5/ Measured using the test load on figure 3, circuit B. See figure 4 for waveforms.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 7

Device	01 through 03		
types			
Case	K, L	3	X
outlines			
Terminal		Terminal symb	ool
number			-
1	PL	PL	PL
2	I ₀	I ₀	I ₀
3	I ₁	I ₁	I ₁
4	l ₂	NC	l ₂
5	l ₃	l ₂	NC
6	I_4	l ₃	l ₃
7	l ₅	I_4	l ₄
8	I_6	l ₅	NC
9	I ₇	I ₆	I ₅
10	I ₈	l ₇	I ₆
11	l ₉	NC	NC
12	GND	I ₈	l ₇
13	ŌE	l ₉	I ₈
14	I/O ₉	GND	l ₉
15	I/O ₈	ŌE	GND
16	I/O ₇	I/O ₉	ŌĒ
17	I/O ₆	I/O ₈	I/O ₉
18	I/O ₅	NC	I/O ₈
19	I/O ₄	I/O ₇	NC
20	I/O ₃	I/O ₆	I/O ₇
21	I/O ₂	I/O ₅	I/O ₆
22	I/O ₁	I/O ₄	I/O ₅
23	I/O ₀	I/O ₃	I/O ₄
24	V _{CC}	I/O ₂	I/O ₃
25		NC	I/O ₂
26		I/O ₁	I/O ₁
27		I/O ₀	I/O ₀
28		V _{CC}	V _{CC}

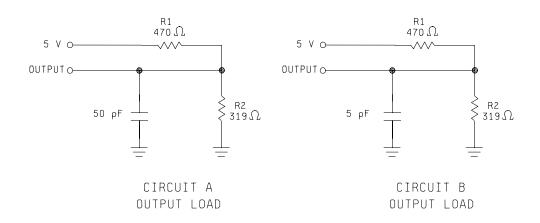
STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 8

Truth table			
Input pins			Output pins
ŌĒ	PL	I	0
Х	Х	Х	Z

NOTES:

- 1. Z = High impedance
- 2. X = Don't care

FIGURE 2. Truth table.



* Including scope and jig (minimum values)

Input pulses

AC test conditions	
Input pulse levels	GND to 3.0 V
Input rise and fall times	≤ 5 ns
Input timing reference levels	1.5 V
Output reference levels	1.5 V

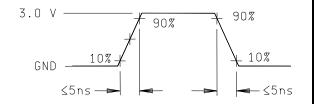
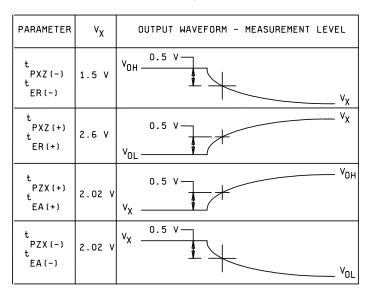


FIGURE 3. Output load circuits and test conditions.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 9

Output control switching waveform



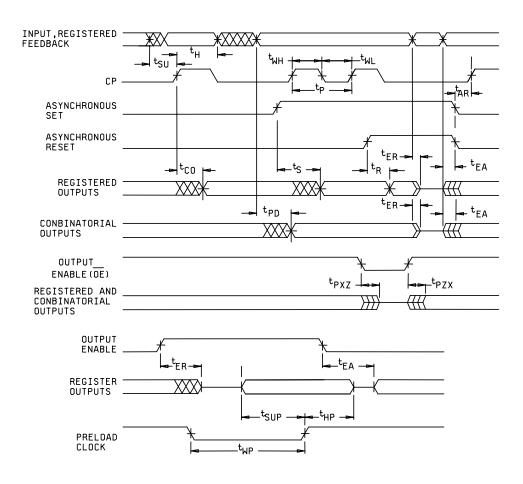


FIGURE 4. Switching waveforms.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 10

4. VERIFICATION

- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements. 1/ 2/ 3/ 4/

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004) for unprogrammed devices	1*, 2, 3, 7*, 8A, 8B
Final electrical test parameters (method 5004) for programmed devices	1*, 2, 3, 7*, 8A, 8B, 9
Group A test requirements (method 5005)	1, 2, 3, 4**, 7, 8A, 8B, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	2, 3, 7, 8A, 8B

- * indicates PDA applies to subgroups 1 and 7.
- 2/ Any or all subgroups may be combined when using high-speed testers.
 3/ ** see 4.3.1c.
- Subgroups 7 and 8 functional tests shall also verify that no cells are programmed for unprogrammed devices or that the altered item drawing pattern exists for programmed devices.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 11

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C_{IN} and C_{OUT} measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance. Sample size is 15 devices with no failures, and all input and output terminals tested.
- d. Subgroups 7 and 8 shall include verification of the truth table.
- e. Unprogrammed devices shall be tested for programmability and ac performance compliance to the requirements of group A, subgroups 9, 10, and 11.
 - (1) A sample shall be selected to satisfy programmability requirements prior to performing subgroups 9, 10, and 11. Twelve devices shall be submitted to programming (see 3.2.3.1). If more than two devices fail to program, the lot shall be rejected. At the manufacturer's option, the sample may be increased to 24 total devices with no more than 4 total device failures allowable.
 - (2) Ten devices from the programmability sample shall be submitted to the requirements of group A, subgroups 9, 10, and 11. If more than two devices fail, the lot shall be rejected. At the manufacturer's option, the sample may be increased to 20 total devices with no more than 4 total device failures allowable.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4 <u>Programming procedures</u>. The programming procedures shall be as specified by the device manufacturer and shall be made available upon request.
- 4.5 <u>Electrostatic discharge sensitivity (ESDS) inspection</u>. ESDS testing shall be performed in accordance with MIL-STD-883, method 3015. ESDS testing shall be measured only for initial qualification and after process or design changes which may affect ESDS classification.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL B	SHEET 12

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43218-3990, or telephone (614) 692-0547.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-90555
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		B	13

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 06-06-22

Approved sources of supply for SMD 5962-90555 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at http://www.dscc.dla.mil/Programs/Smcr/.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9055501KA	0C7V7	PLDC20RA10-35KMB
5962-9055501LA	0C7V7	PLDC20RA10-35DMB
5962-90555013A	0C7V7	PLDC20RA10-35LMB
5962-9055501XA	<u>3</u> /	CG1690BA
5962-9055502KA	0C7V7	PLDC20RA10-25KMB
5962-9055502LA	0C7V7	PLDC20RA10-25DMB
5962-90555023A	0C7V7	PLDC20RA10-25LMB
5962-9055502XA	<u>3</u> /	CG1690AA
5962-9055503KA	0C7V7	PLDC20RA10-20KMB
5962-9055503LA	0C7V7	PLDC20RA10-20DMB
5962-90555033A	0C7V7	PLDC20RA10-20LMB
5962-9055503XA	<u>3</u> /	CG1690CA

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

 Vendor CAGE
 Vendor name

 number
 and address

0C7V7

QP Semiconductor 2945 Oakmead Village Court Santa Clara, CA 95051 - 0812

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for EEPLD - Electronically Erasable Programmable Logic Devices category:

Click to view products by E2v manufacturer:

Other Similar products are found below:

ATF22V10C-10GM/883 ATF22V10C-7JU ATF16V8BQL15JU ATF22V10C-7PX ATF16V8BQL-15SU ATF22V10CQ-15JU

ATF22V10CQZ-20XU ATF16V8B-15PC ATF16V8B-10JU ATF16V8B-15PU ATF16V8BQL-15PU ATF16V8BQL-15SU ATF22V10C
7SX ATF16V8B-15SU-T ATF16V8B-10JU ATF16V8B-15PU ATF22V10C-15PU ATF22V10C-10PU ATF22V10C-10SU

ATF22V10CQZ-20JU ATF22V10C-10JU ATF22V10C-15JU ATF22V10CZ-15JC ATF22V10C-5JX ATF22V10CQZ-20SU ATF22V10C
7SX ATF22V10CQZ20PU ATF16V8B15SU